

# HCAPP: Scalable Power Control for Heterogeneous 2.5D Integrated Systems

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## Summary

- 2.5D systems are limited by the available package pins
  - Many of these pins are used for supplying power
  - Increasing utilization of these pins enables higher performance
- HCAPP
  - ensures a maximum power (eg. package pin limitation)
  - decoupled control through the power supply network
- 21% 43% geomean speedup
  - (on-die and off-die time constraint)



- Next gen computation speedup requires heterogeneous machines

   Currently CPU+GPU systems exist (Summit and Sierra)
- Accelerators provide speedups that are not reliant on Moore's law
- 2.5D integration (shared interposer + specialized dies) allows increased scalability



## Motivation

- New problem: multiple dies share single set of package pins
- Increasing need for power and IO (via package pins)



Image from A Case for Packageless Processors



- Power behavior is very bursty
  - short high-activity periods followed by longer low-activity periods
  - $-P = CV^2 f$
- Keeping the power below the limit = Power Capping





LU Decomposition power consumption at 700 MHz



- Required power behavior detailed by the power limit specification
  - Acceptable power level (50 watts)
  - Acceptable time window (20 µs)
- Time windows dictated by which component will fail first
  - ~20 µs for package pins or ~1 ms for an external voltage regulator (VR)

# **Current Approaches**

- Centralized controllers:
   RAPL/TurboBoost [Intel]
- Software-based control:
  - Isci et al [MICRO39], Joao et al [SIGARCH '13], Lefurgy et al [Cluster Computing v11 '08], SW response time is >50 µs (too slow!)

• Heterogeneous systems:

Harmonia [SIGARCH '15], Komoda et al [ICCD '13],
 DynaCo [SC '13],, Pupil [ASPLOS '16], Co-Cap [SAC '16]

Focused on saving energy or Software-based (too slow!)



- SoCs have many components (processor cores, GPU compute units, etc) in a single package
  - Nvidia Volta V100 has 5120 CUDA cores (in 80 streaming multiprocessors)
  - Large scale means difficult communication for centralized controllers
    - Lots of global wires or use bus



SoCs have many different components

 CPUs, GPUs, accelerators, FPGAs, etc.
 Hard to create a single central algorithm for all combinations



# **Problem Definition**

- How can we take advantage of bursty power consumption to improve performance on average?
  - Bring average and peak power closer together
  - Steer the power to where it is needed
- How can we ensure that the approach will scale as 2.5D systems get larger and larger, and support heterogeneity?
  - Cannot have separate communication for each unit
  - Enable swappable support for different architectures

#### HCAPP: Heterogeneous Constant Average Power Processing

# **Design Requirements**

Requirement	Reason	
Scalable to many components	Needs to work for larger and larger designs in the future	
Support multiple architectures	Needs to enable multiple different configurations of dies in the 2.5D system	
Maintains power cap	Power limit must be upheld for system viability	
Uses extra average power	Use as much power as possible since it is already provisioned	
Fast reaction time	Power cap must be maintained over short time step (~20 μs)	
MOT .		



## **HCAPP** Design







Global controller: maintain power cap through voltage ctrl

### Design



Domain controller: Scale voltage for die, SW interface

### Design



Local controller: Use local metric to improve efficiency





Step 1: Activity change in a component

#### Design



Step 2: Power draw propagates back to global VR





Step 3: Global VR senses new current draw





Step 4: Global controller calculates next voltage (PID)





Step 5: Global VR assigns new global voltage

#### Design



Step 6: Global voltage propagates to domain VR





Step 7: Domain VR senses new global voltage and current





Step 8: Domain ctrl calculates new domain voltage





Step 9: Domain VR applies new domain voltage





Step 10: New domain voltage propagates to component





Step 11: New local voltage determined from domain voltage and local controller





Step 12: Component uses new local voltage and frequency



- PID Tuning
  - Done manually with general methodology
  - First, **increase proportional** (K<sub>P</sub>)
  - Then, increase integral until steady state error is acceptable (K<sub>I</sub>)

- Derivative component not used in this controller

$$V_{ERROR} = \sqrt[3]{P_{SPEC} - P_{NOW}}$$

 $V_{NEXT} = V_{FeedForward} + K_P * V_{ERROR} + K_I * \int V_{ERROR} dt + K_D * \frac{dV_{ERROR}}{dt}$ 

# **Component-Specific Design**

- Local controllers designed to take advantage of local architecture metrics (such as IPC or warp occupancy)
- Scale voltage locally based on metrics to push power to components that need the power
- Used high IPC (CPU) and dynamic warp controllers (GPU) from CAPP and GPU-CAPP work

# **Global Controller Speed**

Component	Response time (ns)	
Voltage Regulator	(36-226)x2 = 72-452	
Sensing Circuitry	50-60	
Controller	10-30	
Power Supply Network	(3-15)x5 = 15-75	
Total	147-617	
HCAPP Cycle Time	1000	

## **Design Summary**

Requirement	HCAPP Related Feature	Status
Scalable to many components	Decentralized control through power network	PASS
Support multiple architectures	Architecture-specific domain controller and local controller logic	PASS
Maintains power cap	PID power control tuned to ensure cap	PASS
Uses extra average power	PID power control increases voltage when power is below cap	PASS
Fast reaction time	Speed of CAPP control is 1 µs	PASS



# **Experimental Setup (System)**

- System was defined as:
  - 1 CPU
  - 1 GPU
  - 1 SHA Accelerator

 Focused on execution time of one benchmark run on each starting at the same time

- Combinations chosen based on benchmark characteristics

# **Experimental Setup (Models)**

- CPU modeled using Sniper simulator with McPAT power model
- GPU modeled using GPGPUSim with GPUWattch

Accelerator modeled as SHA Accelerator [Suresh et al, ESSCIRC'18]



# Experimental Setup (Benchmarks)

- CPU: PARSEC benchmark subset
- GPU: Rodinia benchmark subset
- SHA Accelerator
  - Analytical model with fixed amount of input work

Benchmarks selected to create combinations of interesting power behaviors

# **Experimental Setup**

- Baseline: system with a single fixed global voltage and no local controllers
- Comparison systems:
  - HCAPP with 1µs control period
  - HCAPP with 100µs control period (RAPL-like equivalent)
  - HCAPP with 10ms control period (SW equivalent)

Constraints: 100 W (20 µs window) and 100 W (1 ms window)

# **HCAPP Maximum Power**



RAPL-like and SW-like greatly exceed maximum power 20 µs time window



## **HCAPP** Performance



Average speedup of **+21%** 20 µs time window



#### **HCAPP PPE**



Provisioned Power Efficiency = Average Power / Power Limit Average PPE improved from 69.1% to **79.3%** 20 µs time window

# **HCAPP Maximum Power**



RAPL-like and SW-like still exceed limit, RAPL-like approaches viability 1 ms time window



## **HCAPP** Performance



Average speedup of **+43%** (compared to 36% for RAPL) 1 ms time window



#### **HCAPP PPE**



Average PPE improved from 69.1% to **93.9%** (RAPL: 79.7%) 1 ms time window

## **HCAPP SW Interface**



Simple SW prioritization results in average speedups of **+8.3%** (CPU), **+5.4%** (GPU), and **+12.0%** (SHA)



# **Final Thoughts**

HCAPP is a power management architecture that can:

- Manage heterogeneous systems
- Scale with increasingly large systems in a single package
- Maximize performance under a power limit

Application	Pin power limit	VR power limit
Speedup	+21%	+43%
PPE	+10%	+35%

## **Thank you for watching**